


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	EMBEDDED PROCESSING/26/16206	
1.3 Title of PCI	MDRF QFP Packing Standardization (QFP 20x20x1.4 & 24x24x1.4)	
1.4 Product Category	See list	
1.5 Issue date	2026-03-10	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.1.2 Marketing Manager	Emiliano Mario PICCINELLI
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Indirect material - packing used for packing the direct material (primary base packing) (ex: Wafer canister, Lead frames/wafer/substrates interleaves and containers, etc...)	ST Malta

4. Description of change

	Old	New
4.1 Description	Inner box and bubbles sheet	Inner box
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Packing standardization
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Internal traceability
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7. Timing / schedule

7.1 Date of qualification results	2026-03-10
7.2 Intended start of delivery	2026-04-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16206 Public product.pdf
16206 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC56EL70L5CBOSR	
	SR5E1E570C30F01X	
	SR5E1E770C30F00X	
	SR5E1E770C30F01X	

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